辐射功率：

代码	最小值	最大值	单位	测试条件
P1-4	10	15	mw	IF=100mA

电压分档

代码	[illegible]	最大值	单位	测试条件
N14-5	5.0	5.2	V	IF=100mA
N14-6	5.2	5.4		
N14-7	5.4	5.6		
N14-8	5.6	5.8		
N14-9	5.8	6.0		
N15-1	6.0	6.2		

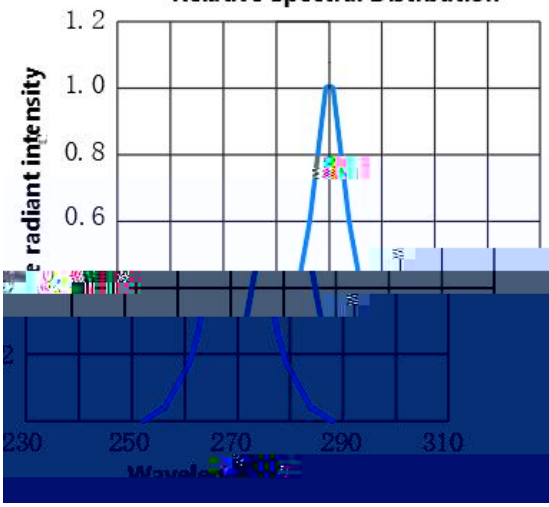
[illegible]

代码	最小值	[illegible]	单位	测试条件
SZ01	260	270	nm	IF=100mA
SZ02	270	280		

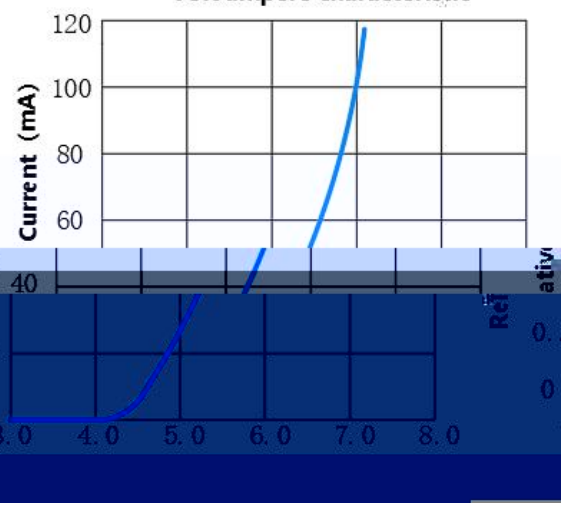
典型特性曲线

Typical Characteristics Curves

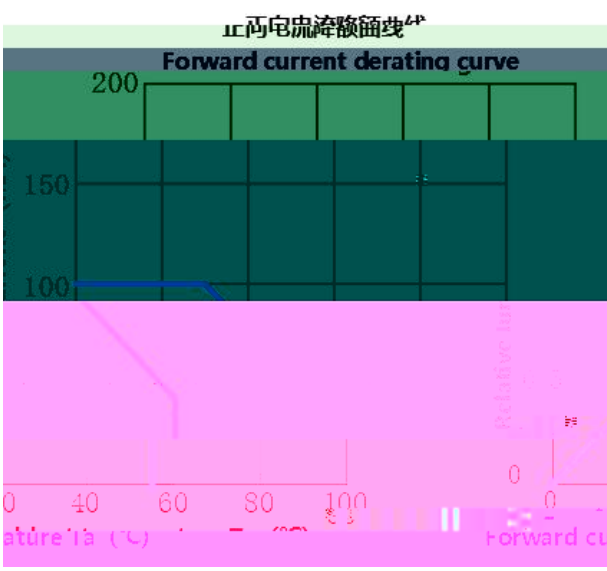
光谱分布曲线
Relative Spectral Distrbution



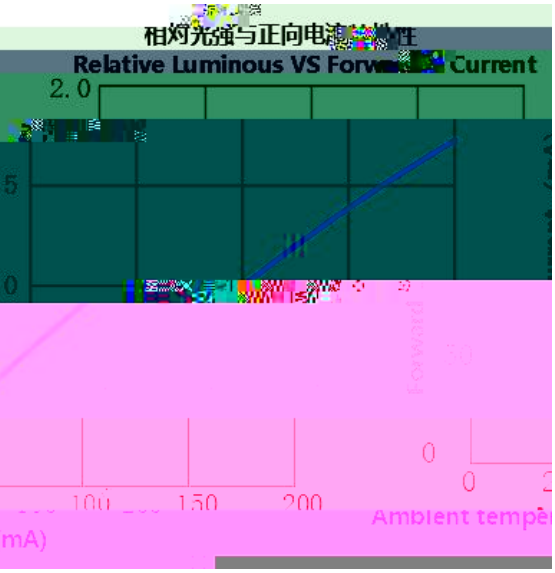
伏安特性
Volt ampere characteristic



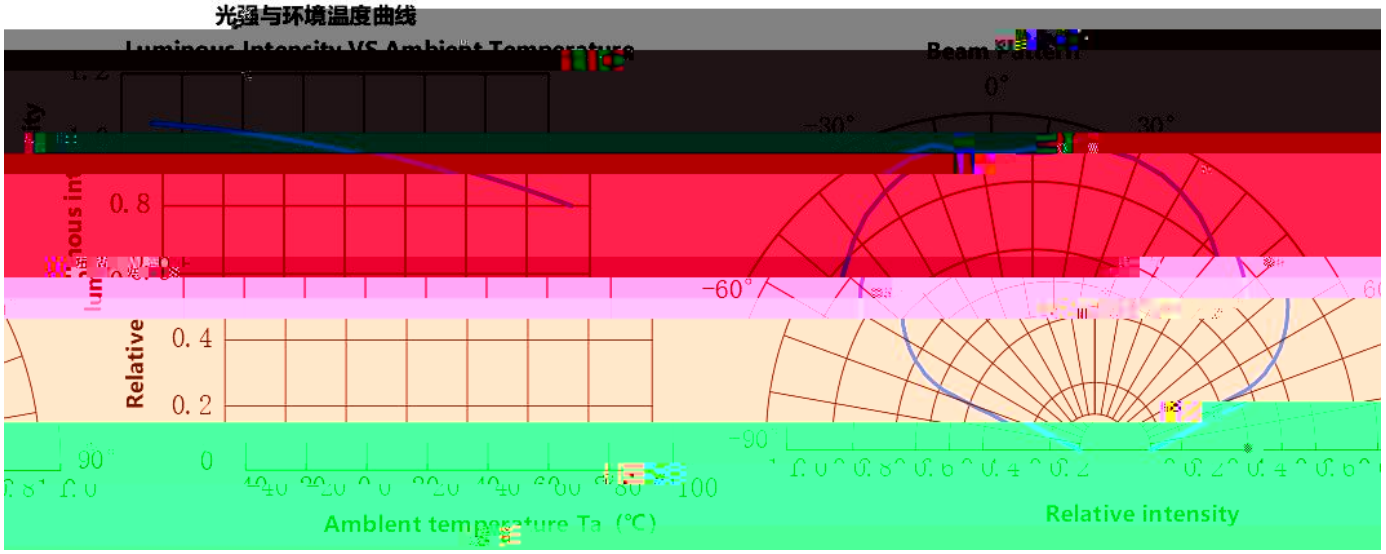
正向电流降额曲线
Forward current derating curve



相对光强与正向电流特性
Relative Luminous VS Forward Current



光强与环境温度曲线
Luminous Intensity VS Ambient Temperature



Beam Pattern

25 5 /Note If not otherwise indicated the test environment temp erature is 25 5

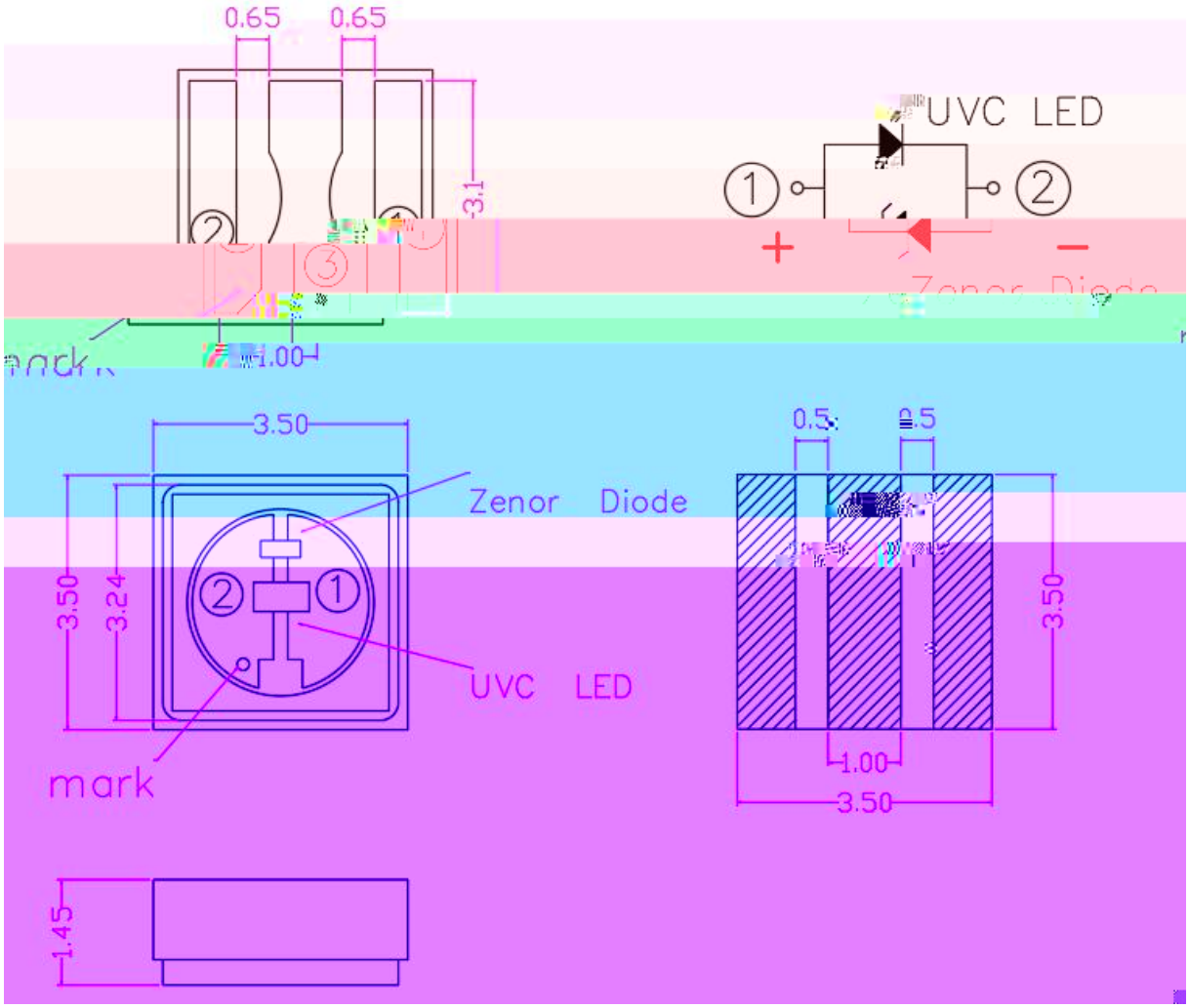
可靠性试验

Reliability Test Items And Conditions

Reliŋ ɤ

外形尺寸

Outline Dimension



All dimensions are in millimeters.

Tolerance is 0.25mm unless otherwise noted

包装（2）

Packaging (2)

◇ 防潮抗静电包装 Moisture Proof and Antti-Electrostic Foil Bag

◇ 外包装箱 Cardboard Box

◇ 标签说明 Label Expantion：

CPN：批号/档位　　LOT：日期/封装颜色

MPN：型号　　VF：电压代码

[illegible]：波长代码　　IV：亮度代码

[illegible]：产地　　QTY：数量

PACKAQE：封装

焊接指导（1）

Guideline for Solder

使用烙铁人手焊接

W

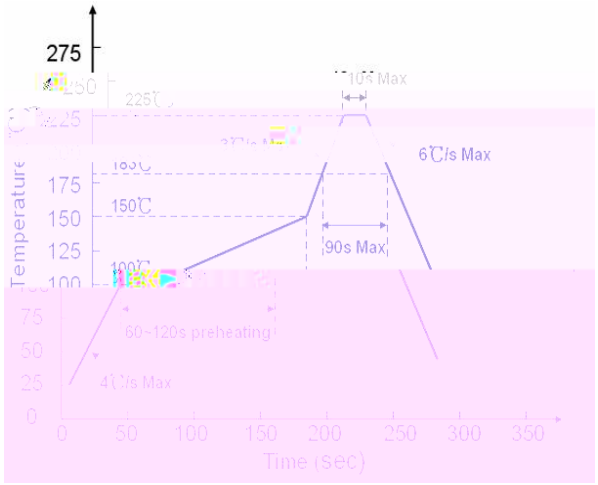
300 3

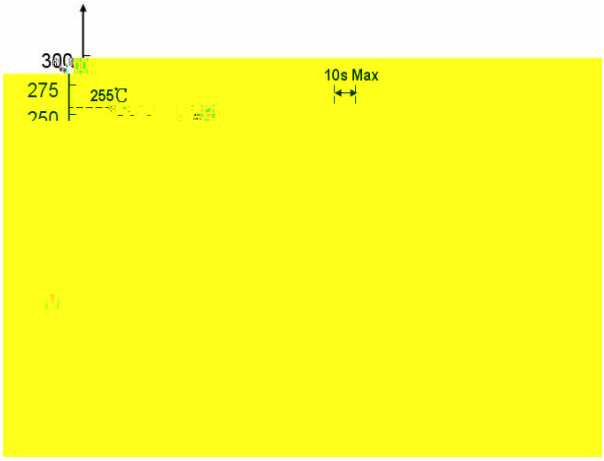
LED

Manual welding is recommended only for repair and heavy industry situations. A soldering iron of less than 30W is recommended to be used in Hand Soldering. Please keep the temperature of the soldering iron under 300 while soldering. Each terminal of the LED is to go for less than 3 second and for one time only.

Be careful because the damage of the product is often started at the time of the hand soldering.

Use the conditions shown in the under Figure of Pb -Free Reflow Soldering.





Lead process lead free

Reflow soldering should not be done more than two times.

LED

Stress on the LEDs should be avoided during heating in soldering process.

After soldering, do not deal with the product before its temperature drop down to room temperature.

240 5 /6S

The recommended maximum welding temperature for the product is 240 5 /6s

焊接指导（2）

Guideline for Soldering (2)

清洗：

30 3 50

30

LED

300W LED

LED

It is recommended that alcohol be used as a solvent for cleaning after soldering. Cleaning is to go under 30 for 3 minutes or 50 for 30 seconds. When using other solvents, it should be confirmed beforehand whether the solvents will dissolve the package and the resin or not.

Ultrasonic cleaning is also an effective way for cleaning. But the influence of Ultrasonic cleaning on LED depends on factors such as ultrasonic power. Generally, the ultrasonic power should not be higher than 300W. Before cleaning, a pretest should be done to confirm whether any damage to LEDs will occur.

* **注意：** PCB

* This general guideline may not apply to all PCB designs and configurations of all soldering equipment. The technics in practise is influenced by many factors, it should be specialized base on the PCB designs and configurations of the soldering equipment..